



Tuesday, April 14th - Workshops

8:00 AM – 12:00 PM	WS1: DfM for Advanced Soldering Technology	Ning-Cheng Lee, Indium Corporation
8:00 AM – 12:00 PM	WS2: The Latest & Hottest SMT Trends: What You Need To Know Today To Survive Tomorrow	Mukul Luthra, Waterfall Technologies
1:00 PM – 5:00 PM	WS3: DfR for Advanced Soldering Technology	Ning-Cheng Lee, Indium Corporation
1:00 PM – 5:00 PM	WS4: Advanced SMT: Process Development And Yield Enhancement Involving Advanced Packages, 3-D Applications, Pip and Pop Assembly	Mukul Luthra, Waterfall Technologies

Wednesday, April 15th – Technical Program

8:00 AM	Registration	Speaker
8:50 AM	Opening Comments	Mei-Ming Khaw, Keysight Technologies
9:00 AM	Keynote Address	Scott Mokler, Intel Corporation
10:00 AM – 10:30 AM	Refreshment Break	
	Session 1: Manufacturing for Reliability	Chair: Mei-Ming Khaw, Keysight Technologies
10:30 AM	Chemical Influences on the Reliability of Complex Assemblies	Bruno Tolla, Kester
11:00 AM	Improving System Quality Through Quality Data	Yvonne Chii Yeo, IBM Corporation
11:30AM	The Development of a 0.3mm Pitch CSP Assembly Process, Part 1: Stencil Printing Considerations	Mark Whitmore, DEK Printing Solutions
12:00 PM	Reliability Assessment of No-clean and Water-soluble Solder Pastes Part I	Wei Hang Teh, Inventec Performance Chemicals
12:30 PM – 2:00 PM	Lunch	
	Session 2: Alternate Solder Alloys & Failure Analysis Techniques	Chair: David Vetharudge, Listech Technology Sdn Bhd
2:00 PM	SMT Soldering with Low Temperature Solder Paste	Kok Kwan Tang, Intel
2:30 PM	Package-on-Package(PoP) Solder Short FA Technique	Afaq Ahmed, Celestica Malaysia Sdn Bhd
3:00 PM – 3:30 PM	Refreshment Break	
	Session 3: Cleaning & Conformal Coating Part 1	Chair: Jonas Sjoberg, Indium Corporation
3:30 PM	A Novel Solution for Circuit Board Protection	Kevin Tan, Henkel
4:00PM	Maintaining OSP Coating Integrity During the Cleaning Process	Doris Lam, ZESTRON Precision Cleaning Sdn Bhd
4:30 PM	Real Time Electronic Cleaning Agent Control	Mike Bixenman, DBA, Kyzen Corporation
5:00 PM	Qualification of Saponified Wash on Ultra Switch PCA	Moon Kin Lee, Keysight Technologies
5:30 PM	Conference Closure	



Thursday, April 16th – Technical Program

8:00 AM	Registration	Speaker
	Session 4: Cleaning & Conformal Coating Part 2	Chair: Ning-Cheng Lee, Ph.D., Indium Corporation
9:00 AM	Innovative Nanocoatings for High Volume Conformal Coating of Electronics	Filip Legein, Europlasma
9:30 AM	Effects Of Flux Residues on Thermal Shock Performance of Conformal Coatings	Phil Kinner, Electrolube
10:00 AM	Electronic Cleaning Fluid Advancements	Mike Bixenman, DBA, Kyzen Corporation
10:30 AM – 11:00 AM	Refreshment Break	
	Session 5: Advanced Packaging Part 1	Chair: Bee Chin, SanDisk
11:00 AM	Low Porosity Pressure Less Sintering of Novel Nano- Ag Paste for Die Attach	Ning-Cheng Lee, Ph.D., Indium Corporation
11:30 AM	COOL Substrate for 2.5D Packaging Technology	Charles Lin, Ph.D., Bridge Semiconductor Corporation
12:00 PM – 1:30 PM	Lunch	
	Session 6: Emerging Manufacturing Technologies	Chair: Mei-Ming Khaw, Keysight Technologies
1:30 PM	Multi-Array PCB Traceability System	Christoph Wimmer, Microscan
2:00 PM	Laser Singulation. Is It A Realistic Alternative To Routers?	Allen Duck, Getech Automation
2:30 PM	Addressing High Precision Automated Optical Inspection Challenges with Unique 3D Technology Solution	Mallika Ramakrishna, CyberOptics Corporation
3:00 PM	Key to Building Solar Panel Efficiently and Effectively	John P. Almirañez, Universal Instruments
3:30 PM – 4:00 PM	Refreshment Break	
	Session 7: Advanced Packaging Part 2	Chair: KL Lim, Plexus
4:00 PM	Enabling the Use of PET Flexible Substrates for Solid State (LED) Lighting Applications	P.H. Tan, Alpha
4:30 PM	Guidelines for Printed Circuit Board Assembly (PCBA) of UTAC Group's Grid Array Package (GQFN) and its Board Level Reliability	Kyaw Ko Lwin, United Test and Assembly Center Ltd
5:00 PM	Ultralow Residue (ULR) Semiconductor Grade Fluxes for Copper Pillar Flip-Chip	Sze Pei Lim, Indium Corporation
5:30 PM	Conference Conclusion	